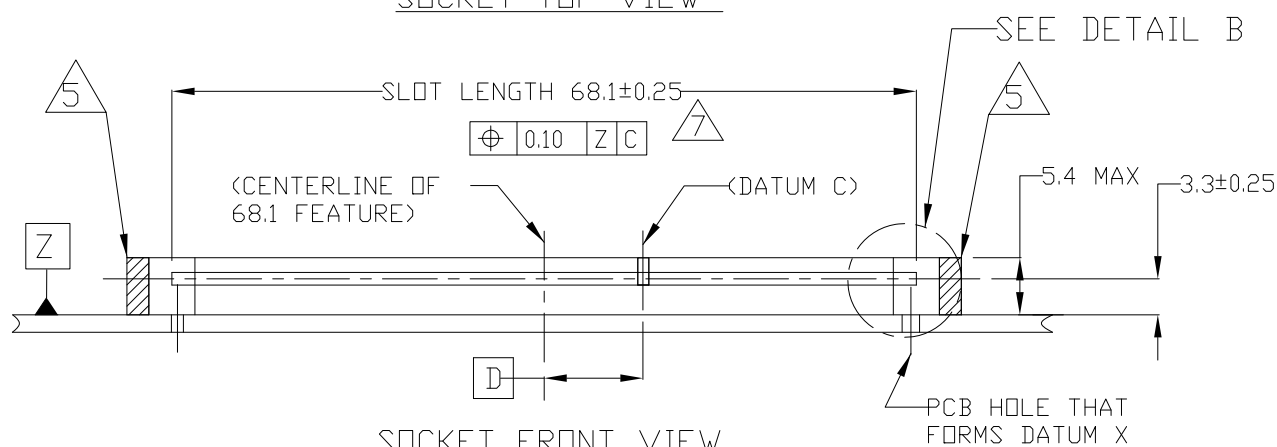
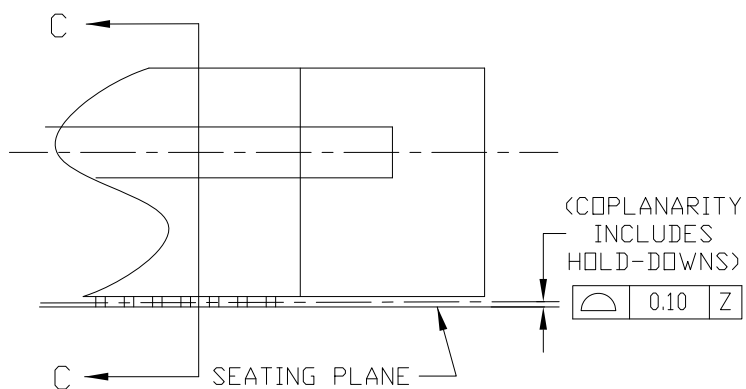


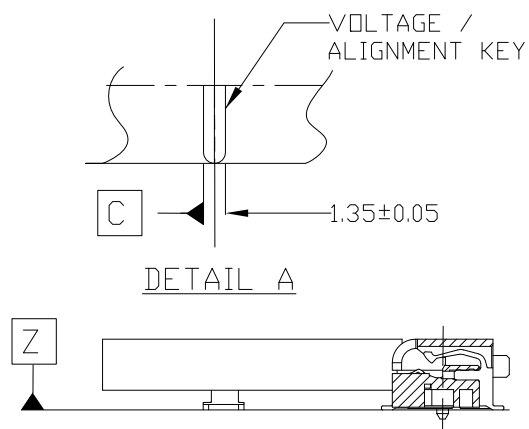
SOCKET TOP VIEW



SOCKET FRONT VIEW



DETAIL B



(STANDARD ORIENTATION)

JEDEC SOLID STATE
PRODUCT OUTLINE
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THIS *REGISTERED OUTLINE* HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

TITLE DDR1/DDR2/DDR3 16b/32b
144 PIN SO DIMM SOCKET
OUTLINE 0.8mm PITCH

DESIGNATOR
SKT

ISSUE
B




DATE
OCT
2012

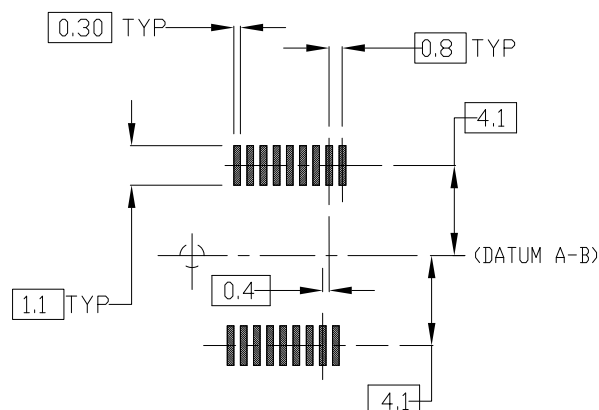
SD-008

SHEET
1 OF 3

VARIATIONS TABLE			
VARIATION	AA 2.5 V (DDR1)	AB 1.8 V (DDR2)	AC 1.50/1.35V (DDR3)
DIMENSION D	14.35	13.60	12.85

NOTES:

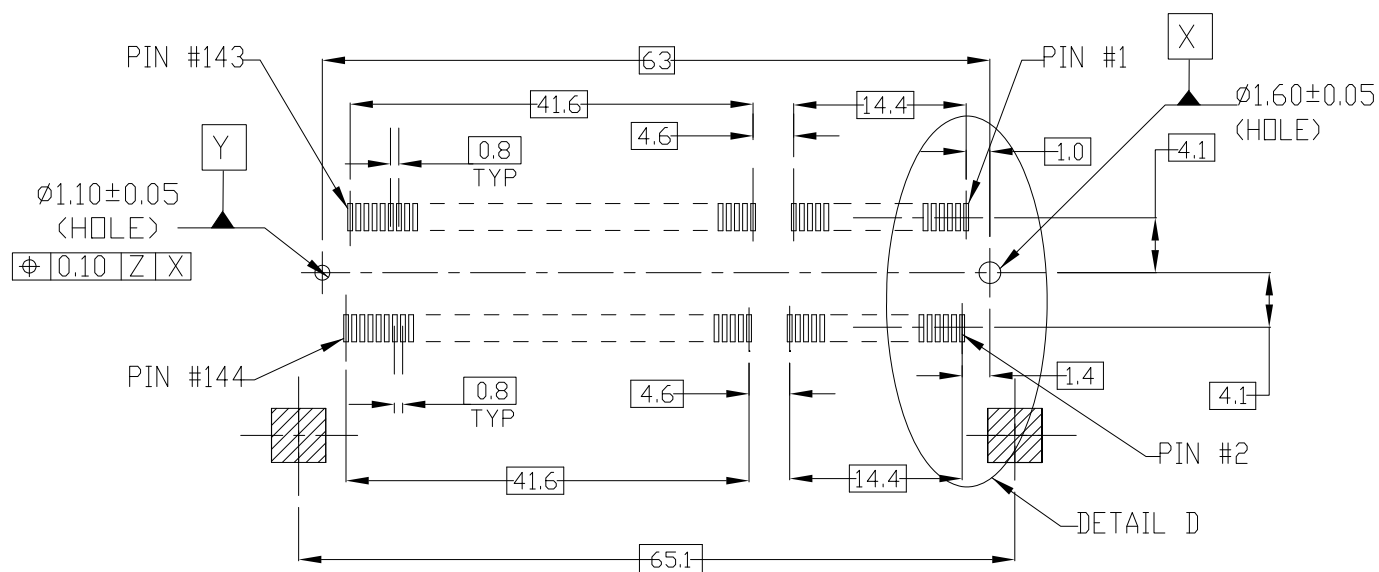
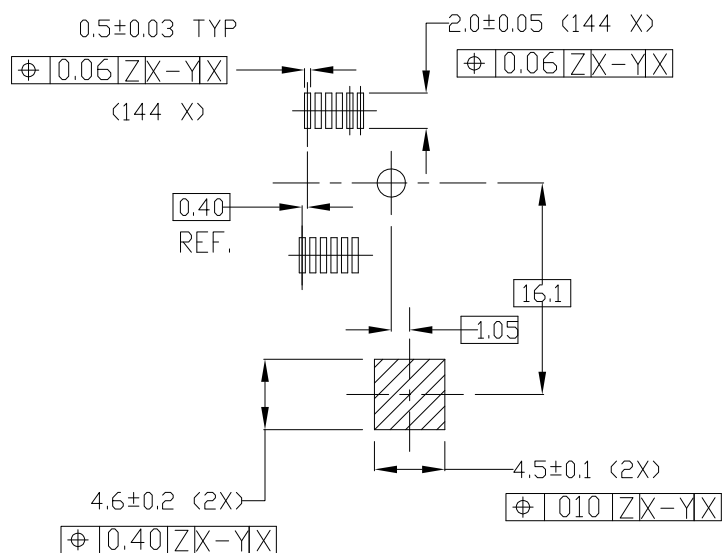
1. DIMENSIONING AND TOLERANCING CONFORM TO Y14.5-2009.
2. ALL DIMENSIONS ARE IN mm.
3. DIMENSION B IS A STATIC, PARALLEL DISPLACEMENT BETWEEN THE CENTERLINE OF MODULE (AT THE INTERFACE/CONNECTOR) AND SURFACE OF HOST/MOTHERBOARD.
4.  KEEPOUT AREA RESERVED FOR SOCKET EJECTORS - BOTH ENDS.
5.  KEEPOUT AREA FOR SOCKET EJECTORS IS HEIGHT RESTRICTED.
6. REFER TO JEDEC MD-274 FOR MODULE DIMENSIONS.
7.  SLOT LENGTH IS SPECIFIC TO THE MATING REGION OF THE SOCKET/INTERFACE THAT FACILITATES ROUGH ALIGNMENT OF THE MODULE.
8. THE FIGURE BELOW IS INCLUDED FOR REFERENCE AND DEPICTS A BOUNDARY AREA (OUTER LOCUS) OF A RECTANGULAR GEOMETRY REPRESENTING THE LEAQ/CONTACT OF THE CONNECTOR. THIS LOCUS INCLUDES ALLOWANCES FOR POSITION AND SIZE TOLERANCES. THE FIGURE SHOWN BELOW DEFINES THE ZONE WITHIN WHICH THE SMT SOLDER LEADS OF THE CONNECTOR MUST ALWAYS BE LOCATED. THIS IS NOT THE MOTHERBOARD FOOTPRINT.



OUTER LOCI OF
TERMINAL POSITIONS

TITLE	DDR1/DDR2/DDR3 16b/32b 144 PIN SO DIMM SOCKET OUTLINE 0.8mm PITCH	DESIGNATOR	SKT	ISSUE	B	DATE	OCT 2012	SHEET	2 OF 3
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APPLICATION NOTES:

PCB LAYOUT - STANDARD ORIENTATION
(TOP VIEW)

DETAIL D

CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE: A	DATE: 18 OCT 2006	ITEM: 14-090
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REVISION HISTORY:

ISSUE: B	DATE: OCT 2012	ITEM: 14-141
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LOCATION	CHANGE FROM:	CHANGE TO:
SHEET 1: TITLE BLOCK	NEW REQUIREMENT	ADDED JEDEC COPYRIGHT
SHEET 2: VARIATIONS TABLE AC	X.XV	1.50/1.35V
SHEET 2: VARIATIONS TABLE AC	(TBD)	(DDR3)
SHEET 2: NOTE 6	... MD -XXX ...	MD-274
SHEET 2: NOTE 8	... LEAQ/CONTACT LEAQ/CONTACT ...
SHEET 1: SOCKET FRONT VIEW	3.3 DIM B	3.3±0.25
SHEET 2: NOTE 8	(LOCUS)	(OUTER LOCUS)
SHEET 2: NOTE 8	_____	ADDED: THE FIGURE SHOWN BELOW...
SHEET 1: SOCKET FRONT VIEW	67.9±0.25	68.1±0.25
ALL SHEETS	TITLE	DDR1/DDR2/DDR3 16b/32b 144 PIN SD DIMM SOCKET OUTLINE 0.8mm PITCH
SHEET 4	MODULE INSERTION APPLICATION NOTE	REMOVE PAGE 4

ISSUE:	DATE:	ITEM:
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LOCATION	CHANGE FROM:	CHANGE TO:

ISSUE:	DATE:	ITEM:
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LOCATION	CHANGE FROM:	CHANGE TO:

TITLE DDR1/DDR2/DDR3 16b/32b 144 PIN SD DIMM SOCKET OUTLINE 0.8mm PITCH	DESIGNATOR SKT	ISSUE B	DATE OCT 2012	SD-008	SHEET i
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